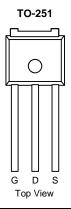


ROHS COMPLIANT

RUH4060K-VB Datasheet

N-Channel 40-V (D-S) MOSFET

PRODUCT SUMMARY						
V _{DS} (V)	R _{DS(on)} (Ω)	I _D (A) ^{a, c}	Q _g (Typ.)			
40	0.0050 at V _{GS} = 10 V	85	120 nC			
40	0.0065 at V _{GS} = 4.5 V	70	120110			

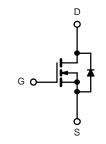


FEATURES

- Trench Power MOSFET
- 100 % R^g and UIS Tested

APPLICATIONS

- Synchronous Rectification
- Power Supplies



N-Channel MOSFET

ABSOLUTE MAXIMUM RATING	S T _A = 25 °C, unle	ss otherwise no	ted	
Parameter		Symbol	Limit	Unit
Drain-Source Voltage		V _{DS}	40	V
Gate-Source Voltage		V _{GS}	± 25	V
	T _C = 25 °C		85 ^{a, c}	
Continuous Drain Current (T = $175 ^{\circ}$ C)	T _C = 70 °C		70 ^c	
Continuous Drain Current (T _J = 175 °C)	T _A = 25 °C	I _D	59 ^b	A
	T _A = 70 °C		53 ^b	A
Pulsed Drain Current	I _{DM} 250	250		
Avalanche Current Pulse	L = 0.1 mH	I _{AS}	80	
Single Pulse Avalanche Energy	L = 0.1 IIIH	E _{AS}	320	V
Continuous Courses Duris Diada Current	T _C = 25 °C	I _S	110 ^{a, c}	A
Continuous Source-Drain Diode Current	T _A = 25 °C	'S	2.6 ^b	A
	T _C = 25 °C		312 ^a	
Maximum Power Dissipation	T _C = 70 °C	PD	200	w
	T _A = 25 °C	FD -	3.13 ^b	vv
	T _A = 70 °C		2.0 ^b	7
Operating Junction and Storage Temperature Range		T _J , T _{stg}	- 55 to 150	°C

THERMAL RESISTANCE RATINGS						
Parameter		Symbol	Typical	Maximum	Unit	
Maximum Junction-to-Ambient ^b	Steady State	R _{thJA}	32	40	°C/W	
Maximum Junction-to-Case	Steady State	R _{thJC}	0.33	0.4	0/10	

Notes:

a. Based on $T_C = 25$ °C.

b. Surface Mounted on 1" x 1" FR4 board.

c. Calculated based on maximum junction temperature. Package limitation current is 110 A.

Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit
Static	•,			.,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,		•••••
Drain-Source Breakdown Voltage	V _{DS}	V _{GS} = 0 V, I _D = 250 μA	40			V
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$	L 050 VA		41		mV/°C
V _{GS(th)} Temperature Coefficient	$\Delta V_{GS(th)}/T_J$	I _D = 250 μA		- 8		
Gate-Source Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_{D} = 250 \ \mu A$	1.2		2.5	V
Gate-Source Leakage	I _{GSS}	$V_{DS} = 0 V, V_{GS} = \pm 20 V$			± 100	nA
		$V_{DS} = 40 \text{ V}, V_{GS} = 0 \text{ V}$			1	μA
Zero Gate Voltage Drain Current	IDSS	$V_{DS} = 40 \text{ V}, \text{ V}_{GS} = 0 \text{ V}, \text{ T}_{J} = 55 ^{\circ}\text{C}$		10		
On-State Drain Current ^a	I _{D(on)}	$V_{DS} \ge 5$ V, V_{GS} = 10 V	120			Α
		V _{GS} = 10 V, I _D = 30 A	0.0050			_
Drain-Source On-State Resistance ^a	R _{DS(on)}	V _{GS} = 4.5 V, I _D = 20 A		0.0065		Ω
Forward Transconductance ^a	9 _{fs}	V _{DS} = 15 V, I _D = 30 A		180		S
Dynamic ^b						I
Input Capacitance	C _{iss}			2380		pF
Output Capacitance	C _{oss}	$V_{DS} = 20 \text{ V}, \text{ V}_{GS} = 0 \text{ V}, \text{ f} = 1 \text{ MHz}$		550		
Reverse Transfer Capacitance	C _{rss}			250		
Total Gate Charge	Qg			120	180	nC
Gate-Source Charge	Q _{gs}	V_{DS} = 20 V, V_{GS} = 10 V, I_D = 20 A		40		
Gate-Drain Charge	Q _{gd}			22		
Gate Resistance	Rg	f = 1 MHz		0.85	1.3	Ω
Turn-On Delay Time	t _{d(on)}			20	30	
Rise Time	t _r	V_{DD} = 20 V, R_L = 1.0 Ω		11	17	
Turn-Off Delay Time	t _{d(off)}	$I_D \cong$ 20 A, V_{GEN} = 10 V, R_g = 1 Ω		77	115	1
Fall Time	t _f			10	15	
Turn-On Delay Time	t _{d(on)}			102	155	ns
Rise Time	t _r	V_{DD} = 20 V, R_L = 1.0 Ω		62	95	-
Turn-Off Delay Time	t _{d(off)}	$I_D \cong 20$ A, V_{GEN} = 4.5 V, R_g = 1 Ω		180	270	
Fall Time	t _f			60	90	
Drain-Source Body Diode Characteristic	s					
Continuous Source-Drain Diode Current	۱ _S	$T_{\rm C} = 25 \ ^{\circ}{\rm C}$			110	A
Pulse Diode Forward Current ^a	I _{SM}				200	
Body Diode Voltage	V _{SD}	I _S = 20 A		0.8	1.2	V
Body Diode Reverse Recovery Time	t _{rr}			50	75	ns
Body Diode Reverse Recovery Charge	Q _{rr}	I _F = 20 A, di/dt = 100 A/μs, T _J = 25 °C		70	105	nC
Reverse Recovery Fall Time	ta	$r_{\rm F} = 20$ A, $a_{\rm F}a_{\rm F} = 100$ A/µs, $r_{\rm J} = 20$ C		30		
Reverse Recovery Rise Time	t _b			20		ns

a. Pulse test; pulse width \leq 300 $\mu s,$ duty cycle \leq 2 %.

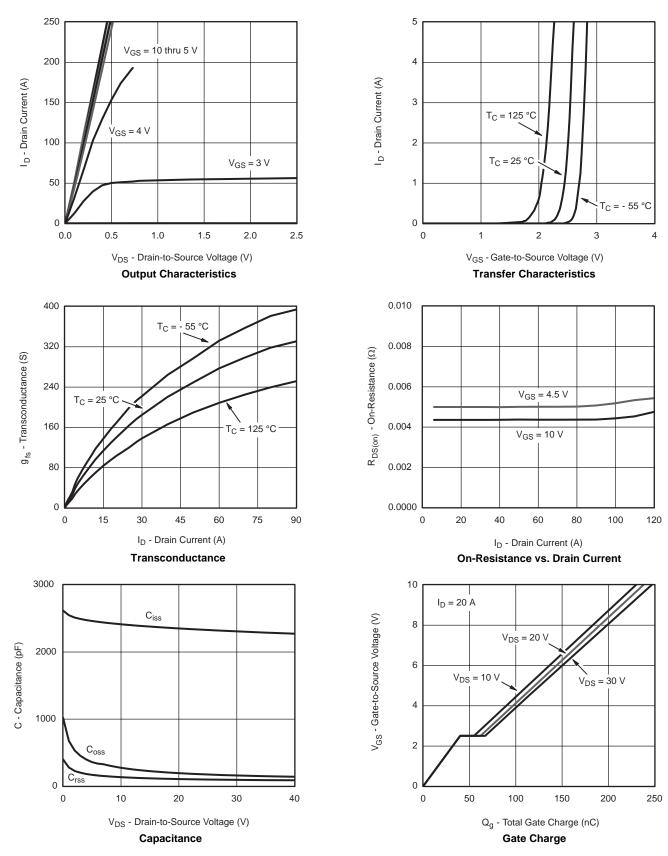
b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

Bsemi

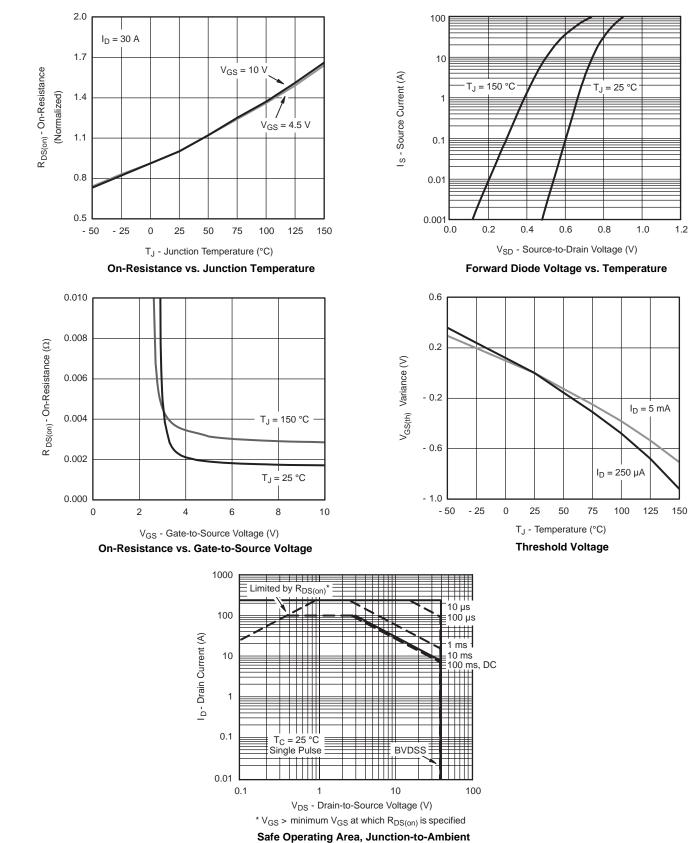


TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



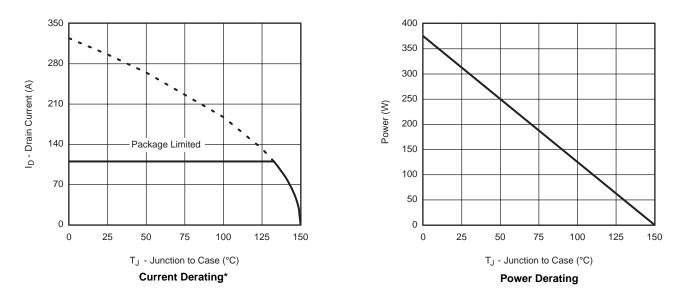
服务热线:400-655-8788





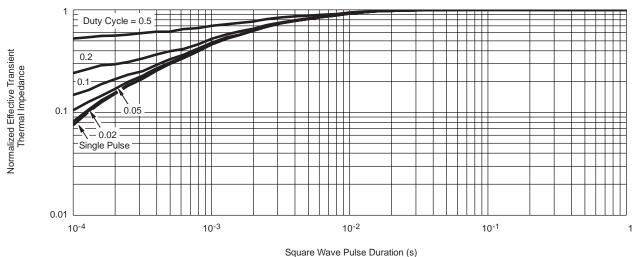
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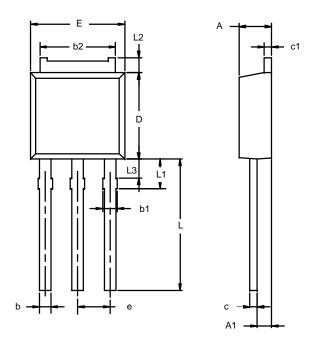
* The power dissipation P_D is based on $T_{J(max)} = 150$ °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.



Normalized Thermal Transient Impedance, Junction-to-Case



TO-251AA (DPAK)



Note: Dimension L3 is for reference only.

	MILLIN	IETERS	INCHES		
Dim	Min	Max	Min	Max	
Α	2.21	2.38	0.087	0.094	
A1	0.89	1.14	0.035	0.045	
b	0.71	0.89	0.028	0.035	
b1	0.76	1.14	0.030	0.045	
b2	5.23	5.43	0.206	0.214	
С	0.46	0.58	0.018	0.023	
c1	0.46	0.58	0.018	0.023	
D	5.97	6.22	0.235	0.245	
Е	6.48	6.73	0.255	0.265	
е	2.28 BSC		0.090 BSC		
L	3.89	9.53	0.153	0.375	
L1	1.91	2.28	0.075	0.090	
L2	0.89	1.27	0.035	0.050	
L3	1.15	1.52	0.045	0.060	
ECN: S-0 DWG: 53	3946—Rev. E 46	, 09-Jul-01	•		



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